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FOR IMMEDIATE RELEASE

Press Release

IMAPS 2017-Raleigh 2 weeks away, visit YINCAE Booth 416 October 10–11, 2017

(Albany, NY) **25 September 2017** – 50th International Symposium on Microelectronics (IMAPS 2017) is 2 weeks away! YINCAE is proud to announce their continued support of the IMAPS organization and will exhibit at booth # 416. The tradeshow will take place at Raleigh Convention Center in Raleigh, North Carolina, on October 10th and 11th. The exhibiting YINCAE team will be available to answer questions and introduce innovative ways YINCAE materials may be of great benefit to current and future projects.

Dr. Wusheng Yin, YINCAE Advanced Materials, LLC. will be presenting his latest white paper, **“High Reliability and High Throughput Ball Bumping Process Solution – Solder Joint Encapsulant Adhesive”** during the CPI Session TP1 Materials and Reliability I at 2:30 pm on Tuesday, October 10, 2017. As pitch and solder ball size continue to shrink, reliability begins to decline rapidly. Currently, the industry has adapted traditional; methods such as capillary underfilling and corner or edge bonding. However, as miniaturization continues, even these methods are creating a bottleneck.

YINCAE has developed solder joint encapsulants adhesives for ball bumping applications to eliminate this bottlenecking and allow miniaturization to continue while improving reliability, thermal cycling performance, drop test performance, and mechanical strength.

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: [YINCAE Website](#).

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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